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In a further variant of the invention, the substrate 14 material is selected from the group comprising: wood, particleboard, chipboard, plastic, metal and cellular materials. In yet a further variant, the veneer 38 material is selected from the group comprising: wood, burl wood, plastic and metal.

In another variant, as illustrated in Figure 3, the means 54 for applying pressure 58 to the top surface 42 of the veneer 38 to conform it to the substrate 14 includes an airtight, flexible container 74. The flexible container 74 has a sealable opening 78 sized and shaped to admit the substrate 14 with the veneer 38 located upon it. Means 82 are provided for evacuating the air 86 from the container 74. When the substrate 14 with the veneer 38 located upon it is inserted into the container 74, the container 74 sealed, and the air 86 evacuated from the container 74, atmospheric pressure 90 will conform the veneer 38 to the upper surface 18 of the substrate 14.

A method, as illustrated in **Figure 3**, for laminating three-dimensional surfaces **94** includes the following steps. Providing a substrate **14**. The substrate **14** is formed of rigid material and has an upper surface **18**, a lower surface **22** and a first perimeter **26**. Forming three-dimensional features **34** commencing at the upper surface **18** of the substrate **14**. The three-dimensional features **34** extend downwardly toward the lower surface **22**. Providing a veneer **38**. The veneer **38** is formed of thin, resilient material and has a top surface **42** and a bottom surface **46**. Applying glue **50** to the bottom surface **46** of the veneer **38** that is suitable for adhering the veneer **38** to the substrate **14**. Positioning the veneer **38** upon the substrate **14**. Applying pressure **58** to the top surface **42** of the veneer **38** will be adhered to the upper

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surface 18 of the substrate 14 and will reflect the three-dimensional features 34 of the substrate 14.

The apparatus 10 and method 94 for laminating three-dimensional surfaces has been described with reference to particular embodiments. Other modifications and enhancements can be made without departing from the spirit and scope of the claims that follow.